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(54) **CERAMIC ELECTRONIC COMPONENT**

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(57) **ABSTRACT**

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A ceramic electronic component includes: a body including dielectric layers and internal electrodes; and external electrodes disposed on the body and connected to the internal electrodes, in which the dielectric layers include a plurality of dielectric crystal grains, an average number of dielectric crystal grains per unit thickness (1 μm) of the dielectric layers is 6 or more, and t_d is 2.0 μm or less, t_d being an average thickness of at least one of the dielectric layers.

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